6-18-03-

Express Mail" mailing label number: EV133913630US

Date of Deposit: June 14, 2002

I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to: Commissioner for Patents, Washington D.C. 20231.

Typed or Printed Name of Person Mailing Paper or Fee: Patricia Aquillon

PATENT Docket No. P1410

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT:

SERGEY LOPATIN

ALEXANDER H. NICKEL

PAUL L. KING

SERIAL NO.:

10/084,563

**EXAMINER: UNASSIGNED** 

FILED:

JUN 1 4 2002

**FEBRUARY 26, 2002** 

ART UNIT 2812

FOR:

METHOD OF REDUCING ELECTROMIGRATION IN A COPPER LINE BY ELECTROPLATING AN INTERIM COPPER-ZINC ALLOY THIN FILM ON A COPPER SURFACE AND A

SEMICONDUCTOR DEVICE THEREBY FORMED

## COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

## TRANSMITTAL LETTER

Dear Sir:

In connection with the above referenced patent application, transmitted here with are the following:

- 1. Information Disclosure Statement (1 pages);
- 2. Information Disclosure Statement By Applicant Form PTO-1449 (1 page);
- 3. U.S. Patent No. 6,197,181 B1 (18 pages);
- 4. U.S. Patent No. 6,022,808 (6 pages);
- 5. Article "A Practical Guide to Semiconductor Processing" (3 pages);
- 6. Article "Electrochemical Codeposition and Electrical Characterization of a Copper-Zinc Alloy Metallization" (2 pages);
- 7. Article "Using Electrochemistry to Improve Copper Interconnect" (4 pages);
- 8. Article "ECD Seed Layer for Inlaid Copper Metallization" (2 pages); and

9. Post card in acknowledgment of-receipt of all transmitted materials.

Please date-stamp the enclosed postcard and return same to the undersigned in acknowledgment of receipt of all transmitted material.

Respectfully submitted,

Victor Flores

Reg. No. 29,638

VF/sgs June 14, 2002 LARIVIERE, GRUBMAN & PAYNE, LLP P.O. Box 3140 Monterey, CA 93942 (831) 649-8800